

### HAT1020RJ-VB Datasheet

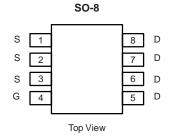
P-Channel 30-V (D-S) MOSFET

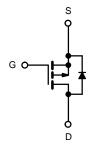
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
	0.033 at V <sub>GS</sub> = - 10 V	- 5.8			
- 30	0.043 at V <sub>GS</sub> = - 6 V	- 5.0			
	0.056 at V <sub>GS</sub> = - 4.5 V	- 4.4			

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted						
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 30		V	
Gate-Source Voltage		V <sub>GS</sub>	± 20			
	T <sub>A</sub> = 25 °C	– I <sub>D</sub>	- 5.8	- 4.1		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		- 4.6	- 3.2		
Pulsed Drain Current		I <sub>DM</sub>	- 30		A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		۱ <sub>S</sub>	- 2.3	- 1.1		
	T <sub>A</sub> = 25 °C	D	2.5	1.3	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	- P <sub>D</sub>	1.6	0.8	vv	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
	t ≤ 10 s	R <sub>thJA</sub>	40	50	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		70	95	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	24	30	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit
Static						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 0.7		- 2.0	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1	
Zero Gate Voltage Drain Current		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 \text{ °C}$			- 5	μA
h		$V_{DS} \le -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$ - 2				
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} \le$ - 5 V, $V_{GS}$ = - 4.5 V	- 5			A
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5.8 A		0.033		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 6 V, I <sub>D</sub> = - 5 A		0.043		Ω
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.4 A		0.056		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5.8 A		13		S
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	I <sub>S</sub> = - 2.3 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.1	V
Dynamic <sup>a</sup>						
Total Gate Charge	Qg			16	24	
Gate-Source Charge	Q <sub>gs</sub>	$V_{\rm DS}$ = - 15 V, $V_{\rm GS}$ = - 10 V, $I_{\rm D}$ = - 3.5 A		2.3		nC
Gate-Drain Charge	Q <sub>gd</sub>			4.5		
Gate Resistance	Rg			8.8		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			14	25	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$		14	25	
Turn-Off Delay Time	t <sub>d(off)</sub>	${\rm I}_{\rm D}\cong$ - 1 A, ${\rm V}_{\rm GEN}$ = - 10 V, ${\rm R}_{\rm g}$ = 6 $\Omega$		42	70	ns
Fall Time	t <sub>f</sub>			30	50	
Source-Drain Reverse Recovery Time $t_{rr}$ $I_F = -1.2 \text{ A}, \text{ dl/dt} = 100$		I <sub>F</sub> = - 1.2 A, dl/dt = 100 A/μs		30	60	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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T<sub>C</sub> = 125 °C

 $V_{GS}$  - Gate-to-Source Voltage (V)

**Transfer Characteristics** 

C<sub>iss</sub>

Coss

15

V<sub>DS</sub> - Drain-to-Source Voltage (V)

Capacitance

20

25

30

3

- 55 °C

4

5

25 °C

2

1

5

0

25

50

T<sub>J</sub> - Junction Temperature (°C)

75

100

125 150

10

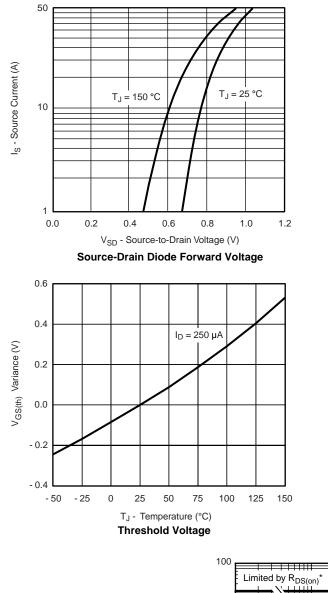
#### 30 30 $V_{GS} = 10 \text{ V}$ thru 6 5 V 25 25 I<sub>D</sub> - Drain Current (A) 20 I<sub>D</sub> - Drain Current (A) 20 15 15 4 V 10 10 5 5 3 V 0 0 0 4 0 2 3 5 1 V<sub>DS</sub> - Drain-to-Source Voltage (V) **Output Characteristics** 1100 0.15 880 0.12 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$ - On-Resistance $(\Omega)$ C - Capacitance (pF) 660 0.09 $V_{GS} = 4.5 V$ 440 0.06 $V_{GS} = 6 V$ 220 0.03 $V_{GS} = 10 V$ Crss 0 0.00 0 0 4 8 12 16 20 I<sub>D</sub> - Drain Current (A) **On-Resistance vs. Drain Current** 1.6 10 $V_{GS} = 10 V$ $I_D = 5.7 A$ V<sub>DS</sub> = 15 V I<sub>D</sub> = 3.5 A 1.4 V<sub>GS</sub> - Gate-to-Source Voltage (V) 8 R<sub>DS(on)</sub> - On-Resistance (Normalized) 1.2 6 1.0 4 0.8 2 0.6 0 - 50 - 25 3.2 0.0 9.6 12.8 16.0 6.4 Qg - Total Gate Charge (nC) **On-Resistance vs. Junction Temperature Gate Charge**

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

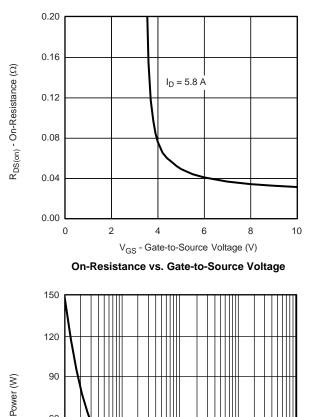
服务热线:400-655-8788







#### TYPICAL CHARACTERISTICS 25 C, unless otherwise noted



10 I<sub>D</sub> - Drain Current (A) 1 ms 1 10 ms HHH 100 ms 1 s 0.1 T<sub>C</sub> = 25 °C 10 s Single Pulse DC 0.01 0.1 1 10 100  $V_{DS}$  - Drain-to-Source Voltage (V) \*  $V_{DS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified Safe Operating Area, Junction-to-Foot

60

30

0

10<sup>-3</sup>

10-2

10-1

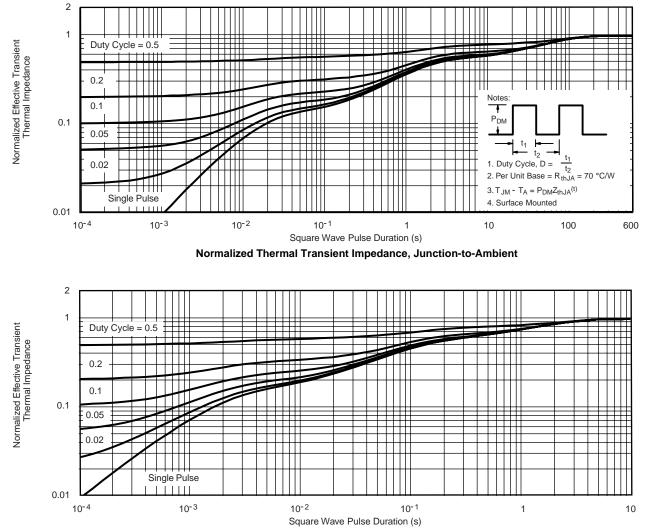
Time (s)

Single Pulse Power, Junction-to-Ambient

1

10





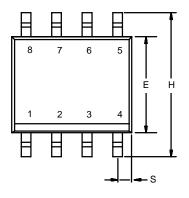
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Foot



#### SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

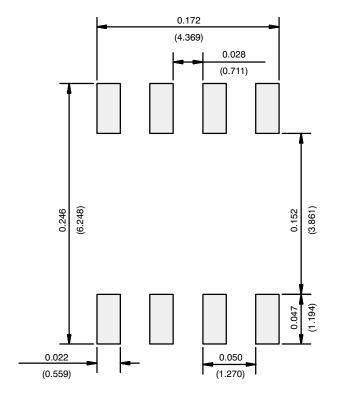




	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



#### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)



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